



500.40269X00

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicants: HABA et al.

Serial No.: 09/888,642

Filed: June 26, 2001

For: ELECTRIC COPPER PLATING LIQUID AND PROCESS FOR  
MANUFACTURING SEMICONDUCTOR INTEGRATED CIRCUIT  
DEVICE USING SAME

Art Unit: 1753

Examiner: E. Wong

**FEB 24 2004**

**AMENDMENT**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

February 17, 2004

Sir:

In response to the Office Action mailed October 16, 2003, please amend the  
above-identified application as listed in the following, and as set forth on the  
following pages:

**Amendments to the Specification;**

**Amendments to the Claims; and**

**Remarks** are included following the amendments.